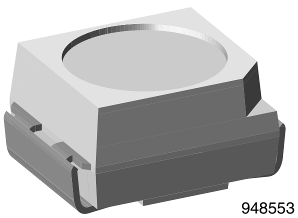
High Speed Infrared Emitting Diode, 940 nm, Surface Emitter Technology



DESCRIPTION

As part of the SurfLight™ portfolio, the VSMY3940X01 is an infrared, 940 nm emitting diode based on surface emitter technology with high radiant intensity, high optical power and high speed, molded in a PLCC-2 package for surface mounting (SMD).

FEATURES

- Package type: surface mount
- Package form: PLCC-2
- Dimensions (L x W x H in mm): 3.5 x 2.8 x 1.75
- AEC-Q101 qualified
- Peak wavelength: λ_p = 940 nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: φ = ± 60°
- Suitable for high pulse current operation
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE
Pb-free
e3
RoHS COMPLIANT
HALOGEN FREE
GREEN (5-2008)

RELEASED FOR APPLICATIONS

Infrared radiation source for operation with CMOS cameras (illumination)

- High speed IR data transmission
- IR touch panels
- 3D TV
- Light curtain

PRODUCT SUMMARY				
COMPONENT	**I_e (mW/sr)**	**φ (deg)**	**λ_P (nm)**	**t_r (ns)**
VSMY3940X01	15	± 60	940	10

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	**PACKAGING**	**REMARKS**	**PACKAGE FORM**
VSMY3940X01-GS08	Tape and reel	MOQ: 7500 pcs, 1500 pcs/reel	PLCC-2
VSMY3940X01-GS18	Tape and reel	MOQ: 8000 pcs, 8000 pcs/reel	PLCC-2

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Pulse peak forward current	t_p/T = 0.5, t_p = 100 μs	I_{FM}	200	mA
Surge forward current	t_p = 100 μs	I_{FSM}	1	A
Power dissipation		P_V	190	mW
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	-40 to +85	°C
Storage temperature range		T_{stg}	-40 to +100	°C
Soldering temperature	acc. figure 10, J-STD-020	T_{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, soldered on PCB	R_{thJA}	250	K/W

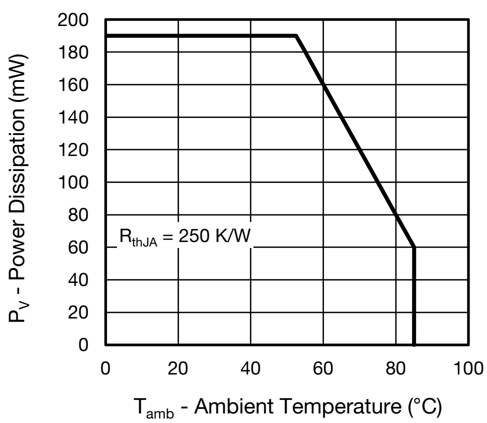


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

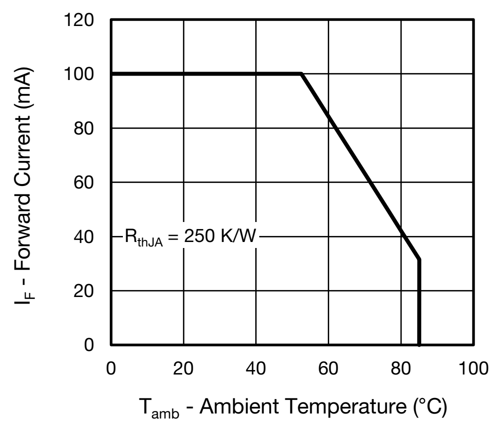


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 100 mA, t_p = 20 ms	V_F		1.44	1.9	V
	I_F = 1 A, t_p = 100 μs	V_F		2.2		V
Temperature coefficient of V_F	I_F = 100 mA	TK_{VF}		-1.6		mV/K
Reverse current		I_R	not designed for reverse operation			μA
Junction capacitance	V_R = 0 V, f = 1 MHz, E = 0	C_j		125		pF
Radiant intensity	I_F = 100 mA, t_p = 20 ms	I_e	8	15	24	mW/sr
	I_F = 1 A, t_p = 100 μs	I_e		120		mW/sr
Radiant power	I_F = 100 mA, t_p = 20 ms	ϕ_e		55		mW
Temperature coefficient of ϕ_e	I_F = 100 mA	$TK\phi_e$		-0.25		%/K
Angle of half intensity		φ		± 60		deg
Peak wavelength	I_F = 20 mA	λ_p	920	940	960	nm
Spectral bandwidth	I_F = 30 mA	$\Delta\lambda$		40		nm
Temperature coefficient of λ_p	I_F = 100 mA	$TK\lambda_p$		0.25		nm/K
Rise time	I_F = 100 mA	t_r		10		ns
Fall time	I_F = 100 mA	t_f		10		ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

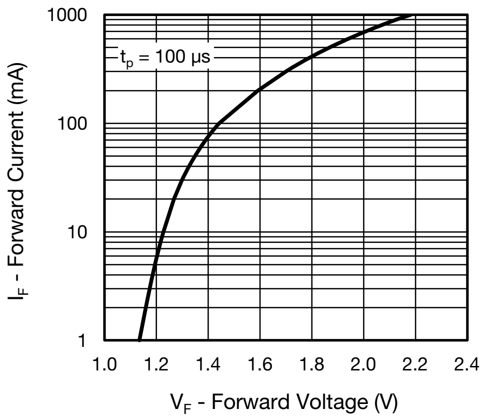


Fig. 3 - Forward Current vs. Forward Voltage

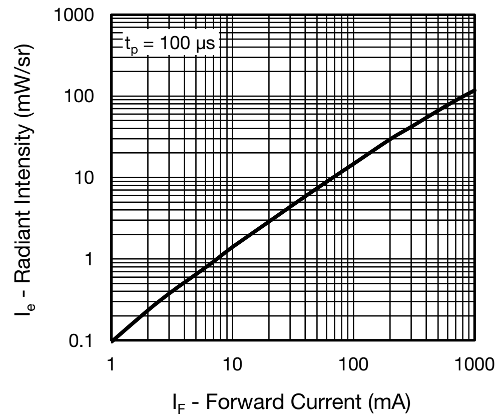


Fig. 6 - Radiant Intensity vs. Forward Current

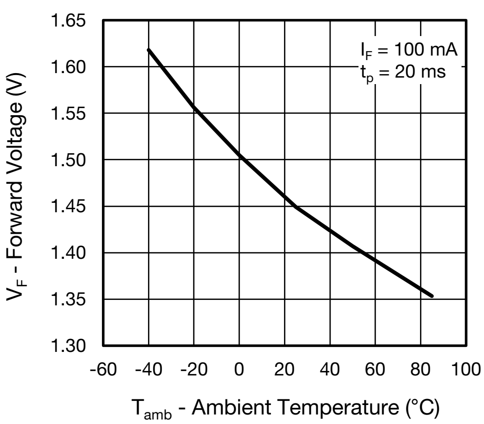


Fig. 4 - Forward Voltage vs. Ambient Temperature

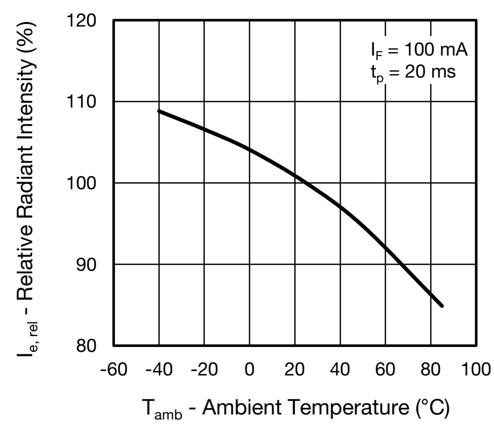


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

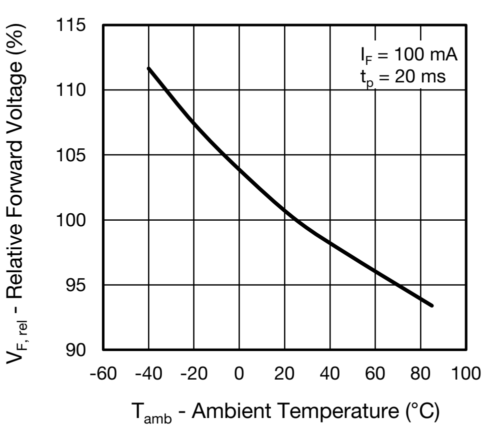


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

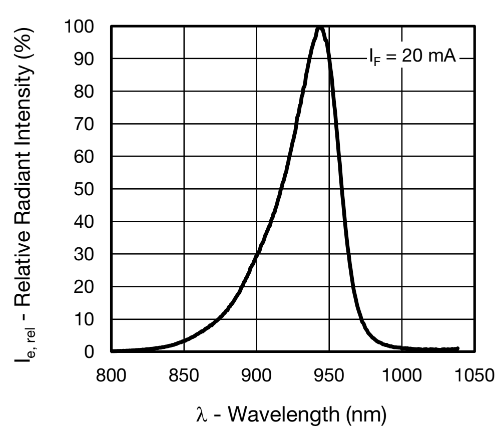


Fig. 8 - Relative Radiant Intensity vs. Wavelength

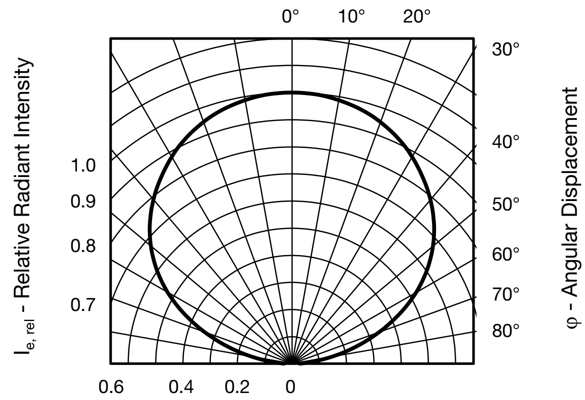
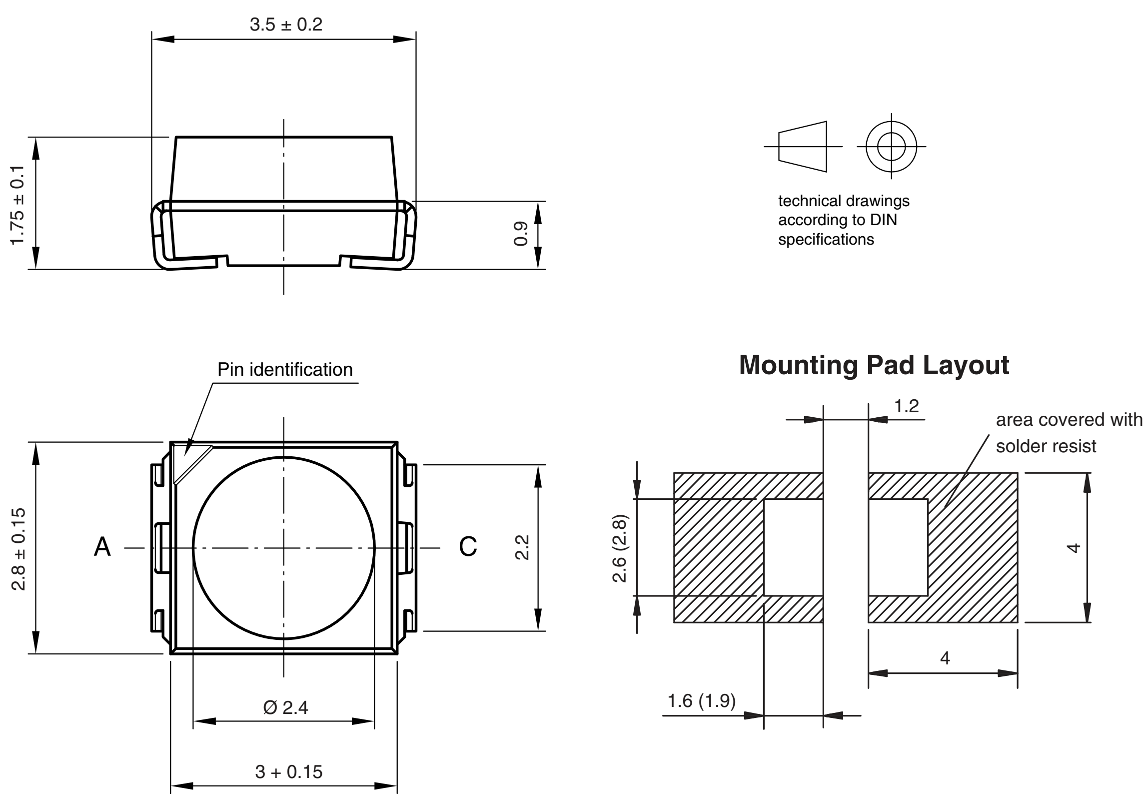


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

PACKAGE DIMENSIONS in millimeters



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SOLDER PROFILE

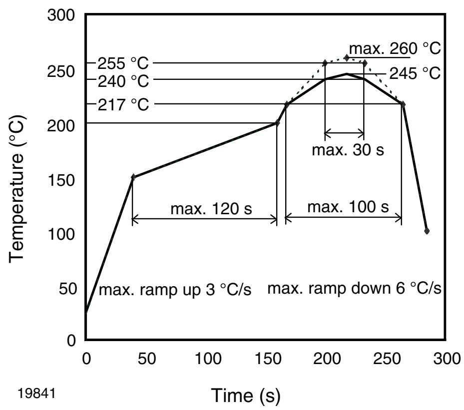

Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:
Floor life: 168 h
Conditions: T_{amb} < 30 °C, RH < 60 %
Moisture sensitivity level 3, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

TAPE AND REEL

PLCC-2 components are packed in antistatic blister tape (DIN IEC (CO) 564) for automatic component insertion. Cavities of blister tape are covered with adhesive tape.

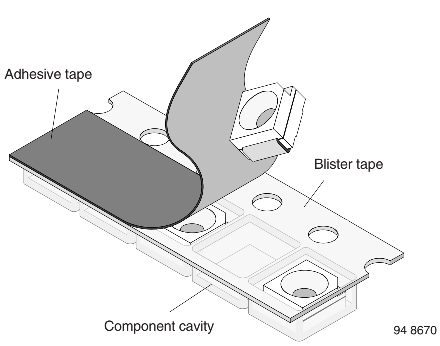

Fig. 11 - Blister Tape

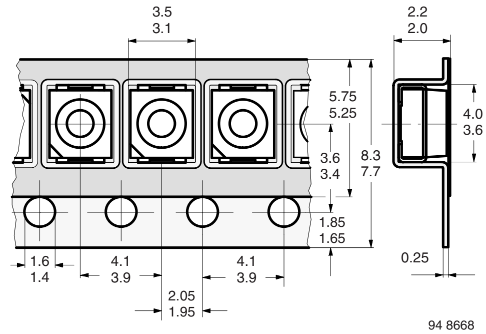

Fig. 12 - Tape Dimensions in mm for PLCC-2

MISSING DEVICES

A maximum of 0.5 % of the total number of components per reel may be missing, exclusively missing components at the beginning and at the end of the reel. A maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components.

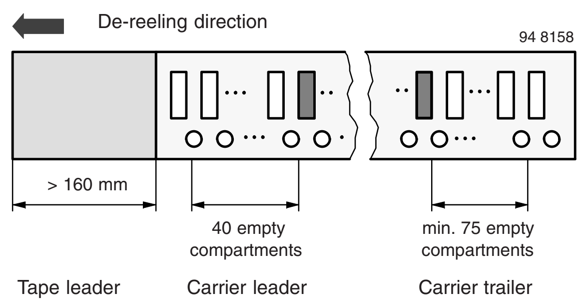

Fig. 13 - Beginning and End of Reel

The tape leader is at least 160 mm and is followed by a carrier tape leader with at least 40 empty compartments. The tape leader may include the carrier tape as long as the cover tape is not connected to the carrier tape. The least component is followed by a carrier tape trailer with a least 75 empty compartments and sealed with cover tape.

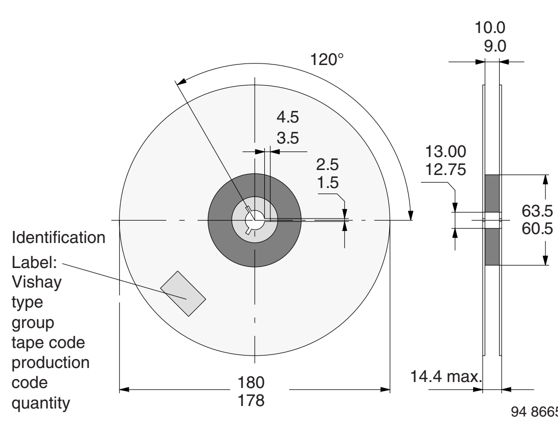

Fig. 14 - Dimensions of Reel-GS08

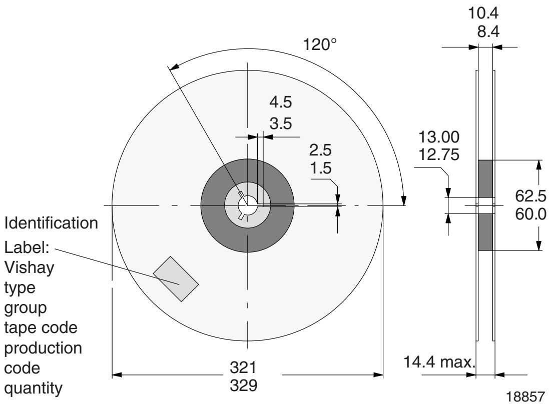

Fig. 15 - Dimensions of Reel-GS18

COVER TAPE REMOVAL FORCE

The removal force lies between 0.1 N and 1.0 N at a removal speed of 5 mm/s. In order to prevent components from popping out of the blisters, the cover tape must be pulled off at an angle of 180° with regard to the feed direction.

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